

10/711,185

**IN THE SPECIFICATION:**

Please substitute the following paragraph for the same-numbered paragraph in the application:

[Para 23] In another embodiment shown in Figure 3, the invention provides a conductive interconnection 300 that has a spherical-shaped (rounded) polymer 302 and metal projections 304 extending towards the polymer from the integrated circuit device 110 and/or the device carrier 112. Each of the metal projections 304 has approximately the same height. These metal projections 304 extend partially into the polymer 302 across the width of the polymer 302 and can have a cone shape (which is triangular when viewed in cross-section). The projections 304 can extend from either or both the integrated device 110 and the device carrier 112. In this embodiment, the polymer 302 also includes metal particles. Preferably, the projections 304 are formed first on the device 110 and/or the carrier 112 by depositing a metal layer and then patterning the metal layer into the projection shapes 304. Then, the polymer 302 is deposited on either the device 110 or the carrier 112 and the device 110 and the carrier 112 are then joined together.